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ABSTRACT OF THE DISCLOSURE

Transfer and processing of semiconductor wafers are performed while maintaining the wafer surfaces in a vertical orientation by holding the water substrate with electrostatic chucking of the rear face thereof. Thereby, the floor area of the transfer and processing system becomes almost the same regardless of the wafer size. Because only the back of the wafer comes in contact with a transfer member, the wafer front surface is kept clean and moreover wafer transfer can be done quickly.

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